



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-08-22
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB75NF75LT4	T2D2*E37HB32	A	3068	2017-08-22
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-9.15-4.5	2	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.16	Die back side metal - Leadframe metal	118
Lead	12.93	Soft solder	9370
Antimony trioxide	6.82	Encapsulation	4942

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T2D2*E37HB32					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	15.097	mg	supplier	die	Silicon (Si)	7440-21-3		14.599	mg	967013	10579
				supplier	metallization	Aluminium (Al)	7429-90-5		0.284	mg	18812	206
				supplier	Passivation	Silicon Oxide	7631-86-9		0.079	mg	5233	57
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	464	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.086	mg	5696	62
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.007	mg	464	5
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.035	mg	2318	25
				supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	998593	563433
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	460	261
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	840	474
Leadframe	Copper & its alloys	778.632	mg	supplier	metallization	Nickel (Ni)	7440-02-0		0.077	mg	99	56
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	12.931	mg	954952	9370
				supplier	solder	Silver (Ag)	7440-22-4		0.339	mg	25035	246
				supplier	solder	Tin (Sn)	7440-31-5		0.271	mg	20013	196
				supplier	wire	Aluminium (Al)	7429-90-5		1.703	mg	995906	1234
Soft solder	Solder	13.541	mg	JIG - R	solder	Magnesium (Mg)	7439-95-4		0.007	mg	4094	5
				supplier	metallization	Silica, vitreous	60676-86-0		458.236	mg	806000	332055
				supplier	solder	Epoxy Cresol Novolak	29690-82-2		39.797	mg	70000	28838
				supplier	metallization	Phenol resin	9003-35-4		22.741	mg	40000	16479
				supplier	metallization	Biphenyl epoxy resin	85954-11-6		34.112	mg	60000	24719
				supplier	metallization	Antimony Trioxide	1309-64-4		6.822	mg	11999	4943
				supplier	metallization	Brominated Epoxy Resin	40039-93-8		3.980	mg	7000	2884
				supplier	metallization	Carbon black	1333-86-4		2.843	mg	5001	2060
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804